

AM2520MBCK03

BLUE

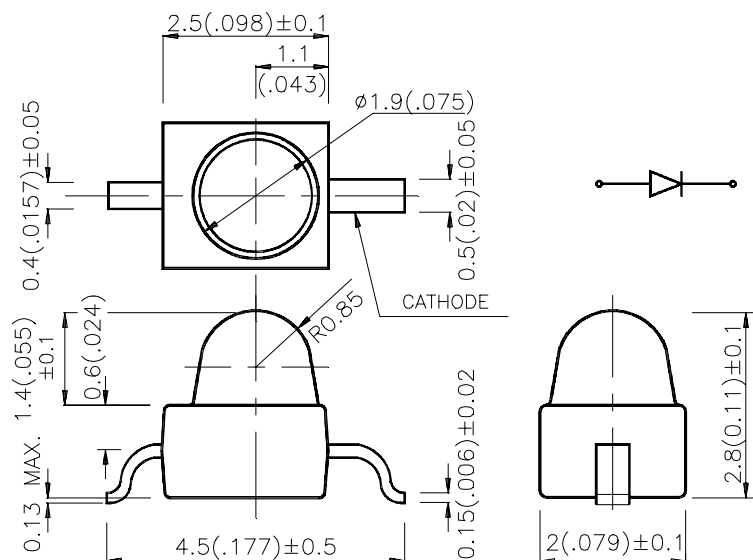
### Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- GULL WING LEAD.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE : 1000PCS / REEL.

### Description

The Blue source color devices are made with GaN on SiC Light Emitting Diode. Static electricity and surge damage the LEDs. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. All devices, equipment and machinery must be electrically grounded.

### Package Dimensions



### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2θ1/2
AM2520MBCK03	BLUE(GaN )	WATER CLEAR	10	30	20°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

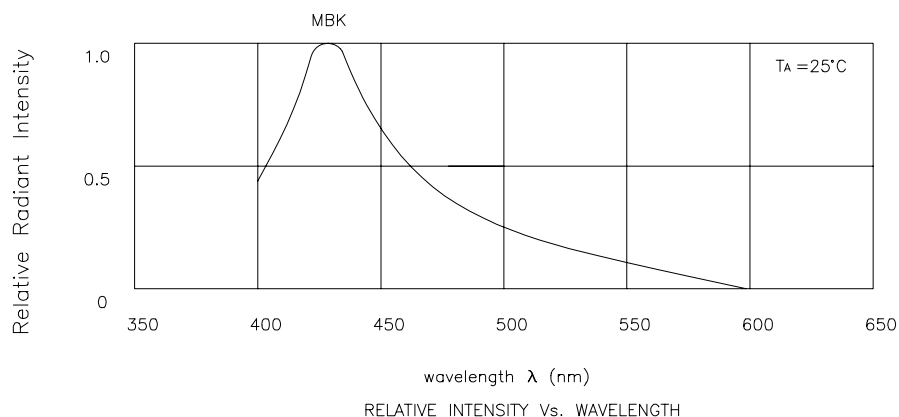
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Blue	430		nm	I <sub>F</sub> =20mA
λ <sub>D</sub>	Dominate Wavelength	Blue	466		nm	I <sub>F</sub> =20mA
Δλ <sub>1/2</sub>	Spectral Line Half-width	Blue	60		nm	I <sub>F</sub> =20mA
C	Capacitance	Blue	100		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub>	Forward Voltage	Blue	4.0	4.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Blue		10	uA	V <sub>R</sub> = 5V

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

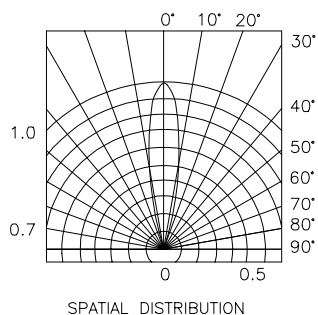
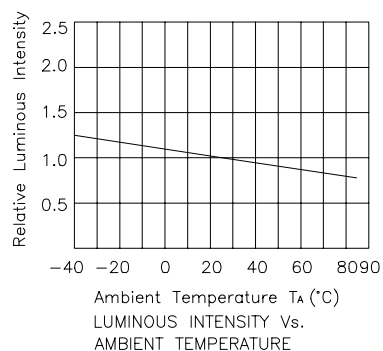
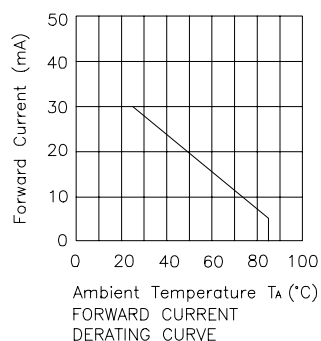
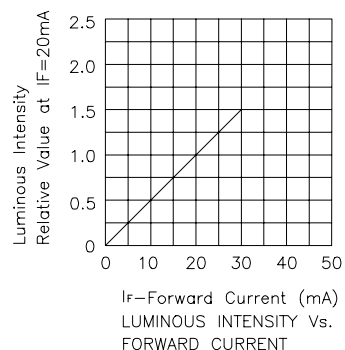
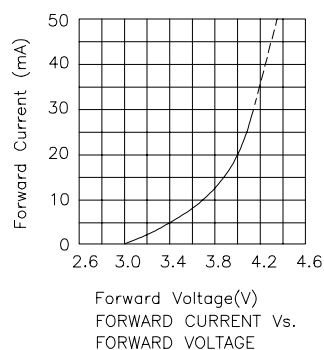
Parameter	Blue	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



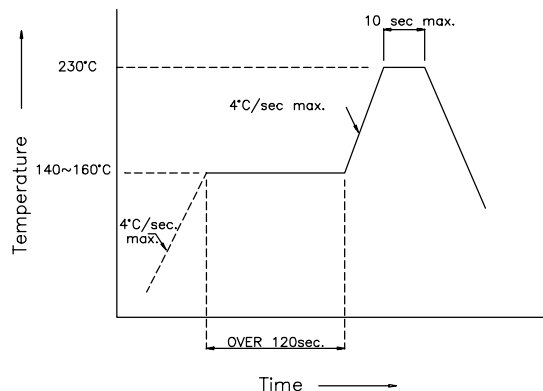
## Blue AM2520MBCK03



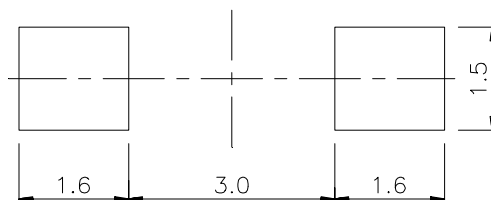
## AM2520MBCK03

### SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



### Recommended Soldering Pattern (Units : mm)



### Tape Specifications (Units : mm)

